

FIG. 2

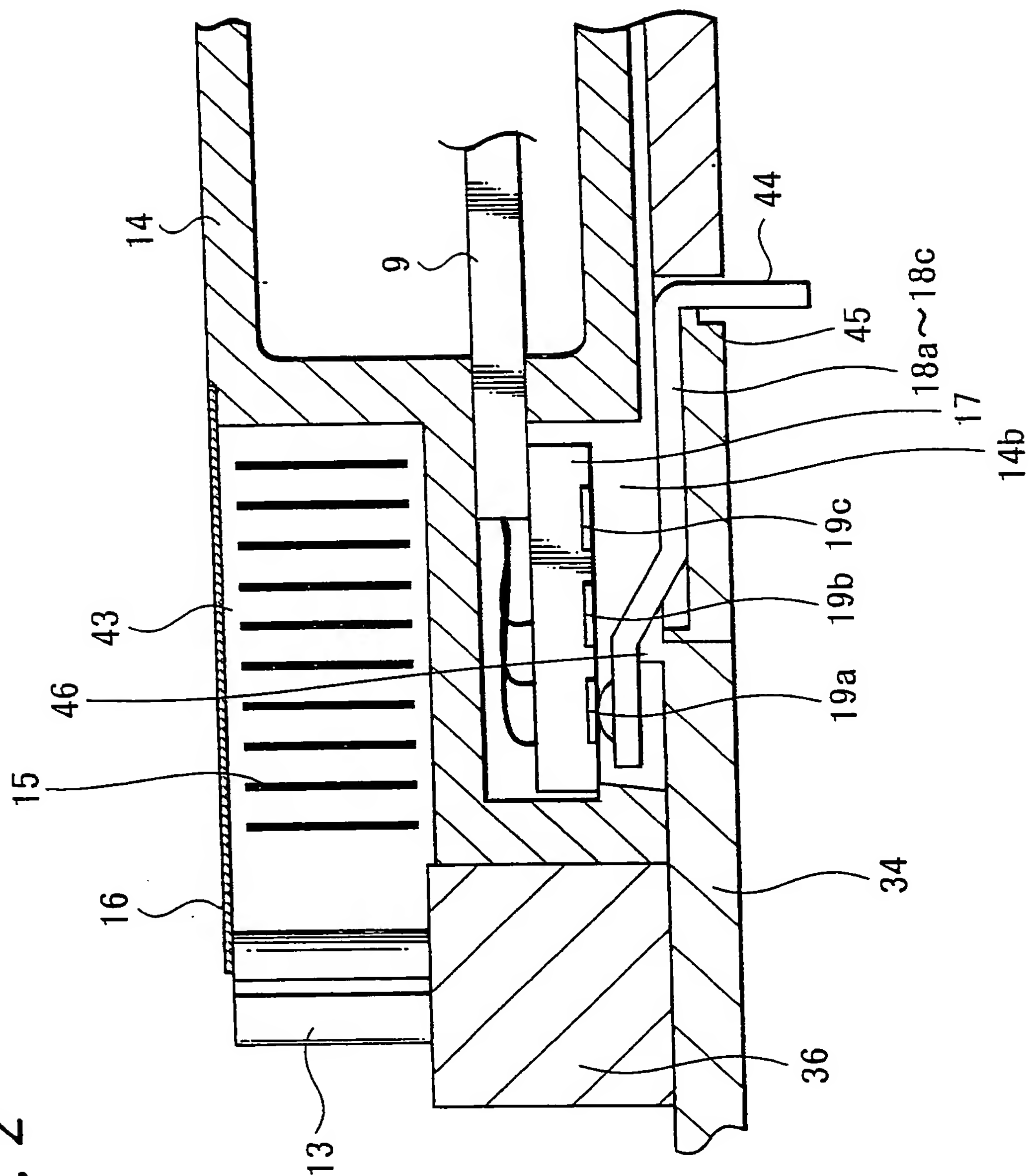
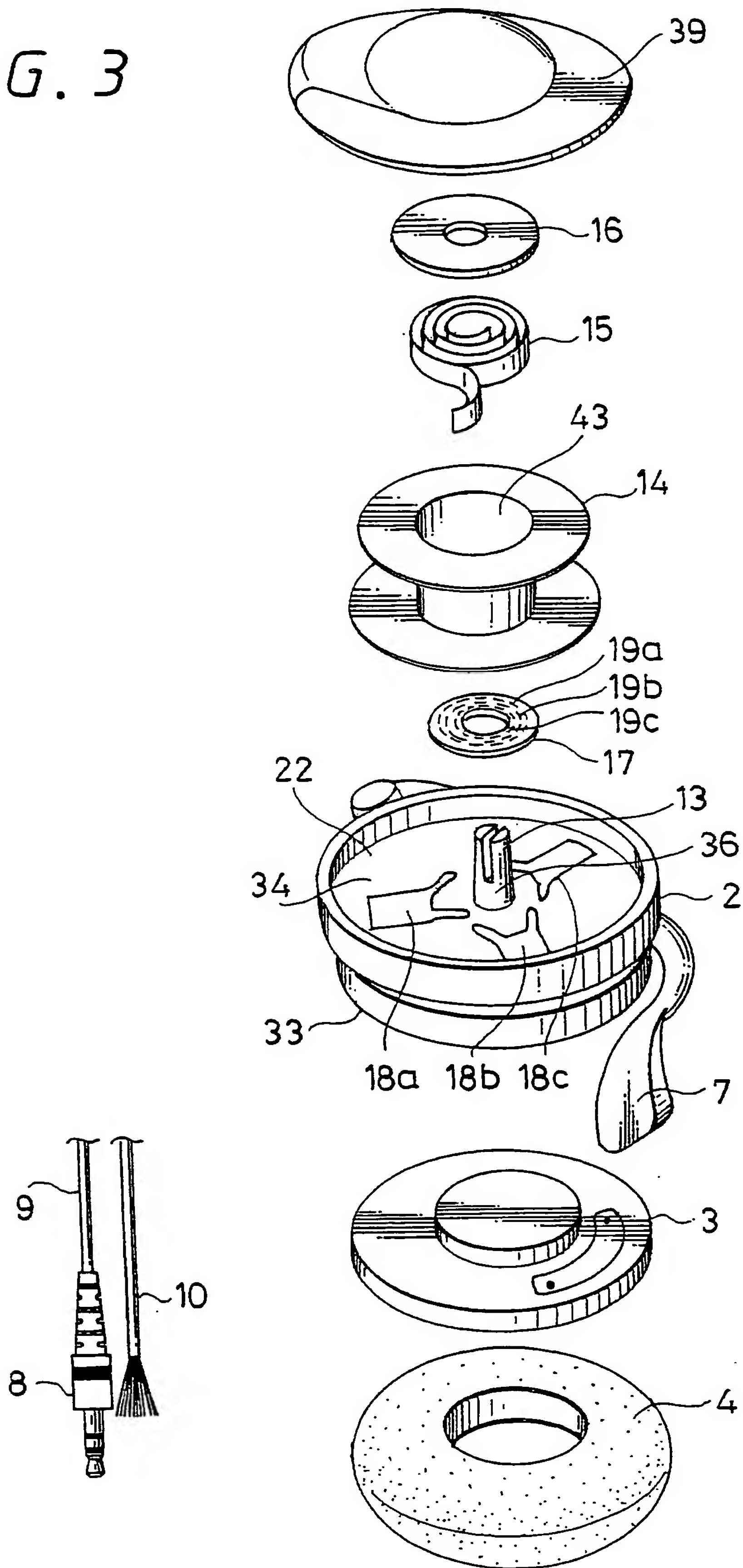


FIG. 3



G. 4A

This diagram shows a cross-sectional view of a semiconductor device 1L. The device features a substrate 2 with a top layer 10 and a bottom layer 34. A central region 14 contains a series of vertical structures 15, 16, and 17. On either side of this central region are two groups of circular elements, likely solder balls or vias, labeled 14a and 14b. The device is mounted on a base 4, which is connected to a circuit board 3. The base 4 is secured by a solder layer 33. The entire assembly is protected by a top layer 14d and a bottom layer 14e. Various other components are labeled with numbers 1 through 40, including 1a, 18a~18c, 19a~19c, 32, 35, 36, 37, and 39.

FIG. 5B

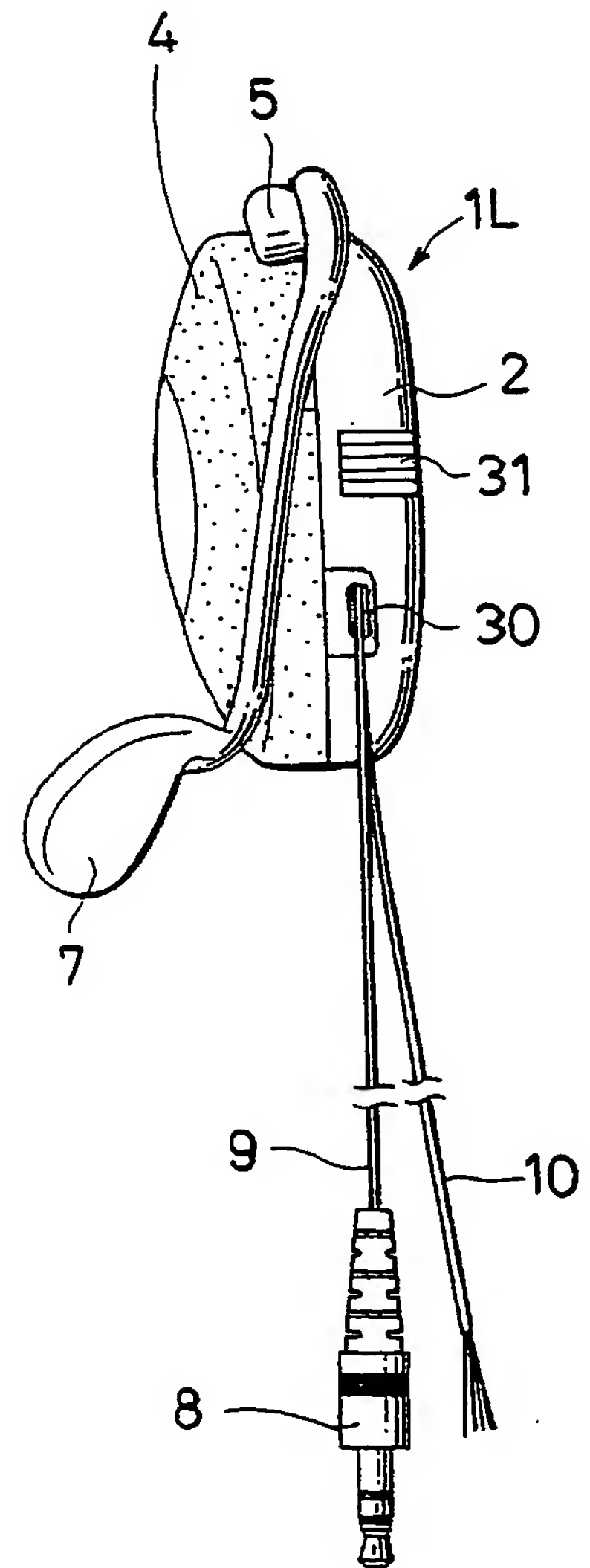
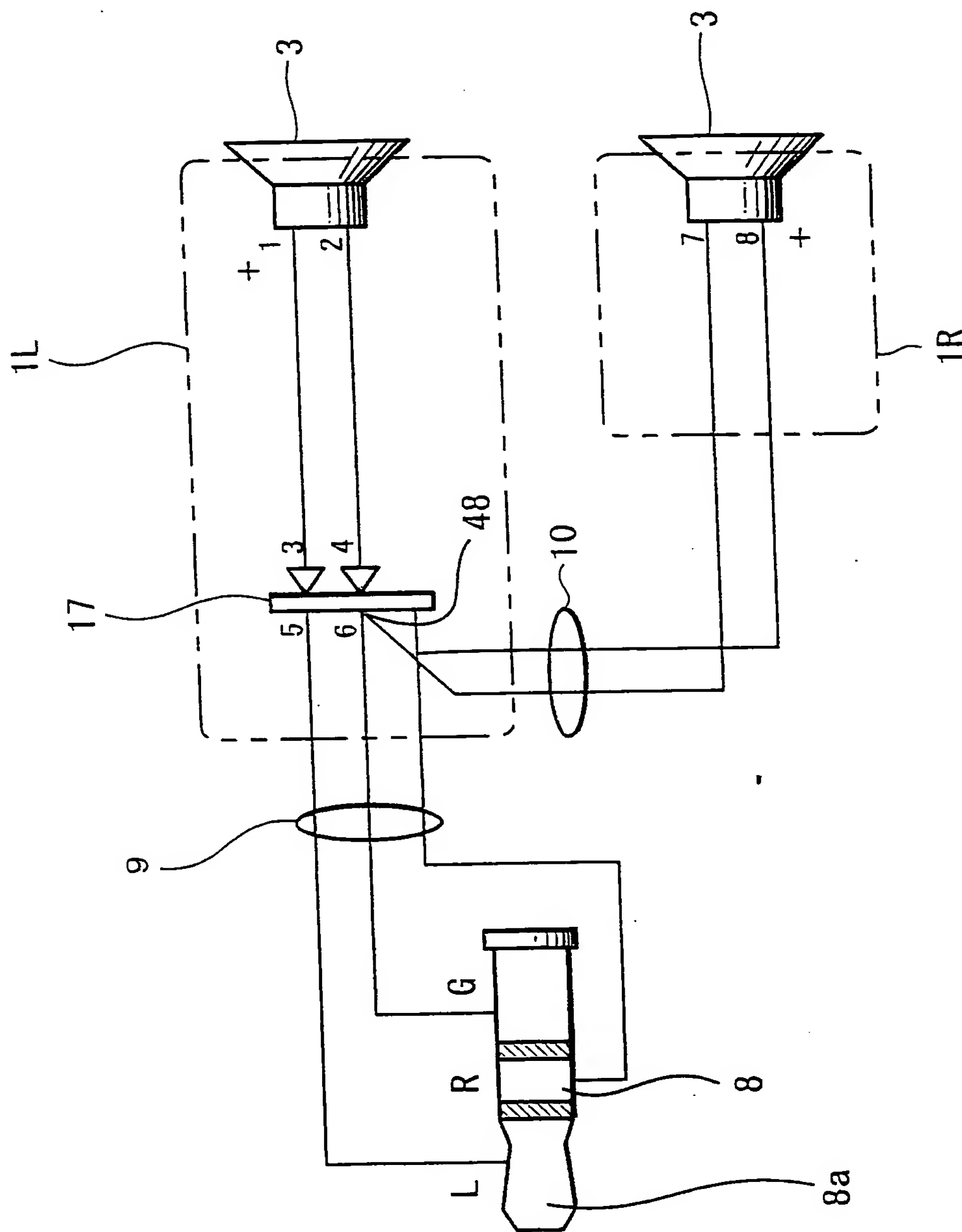


FIG. 6



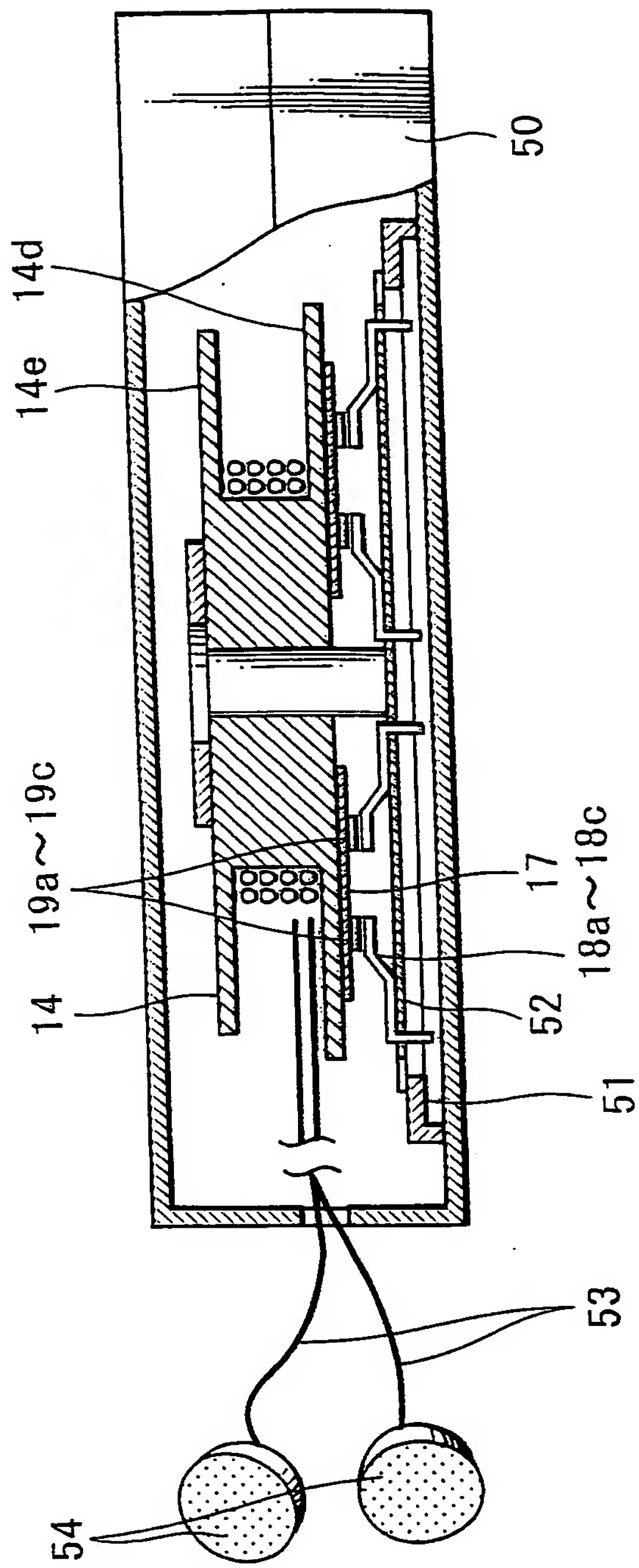


FIG. 7A

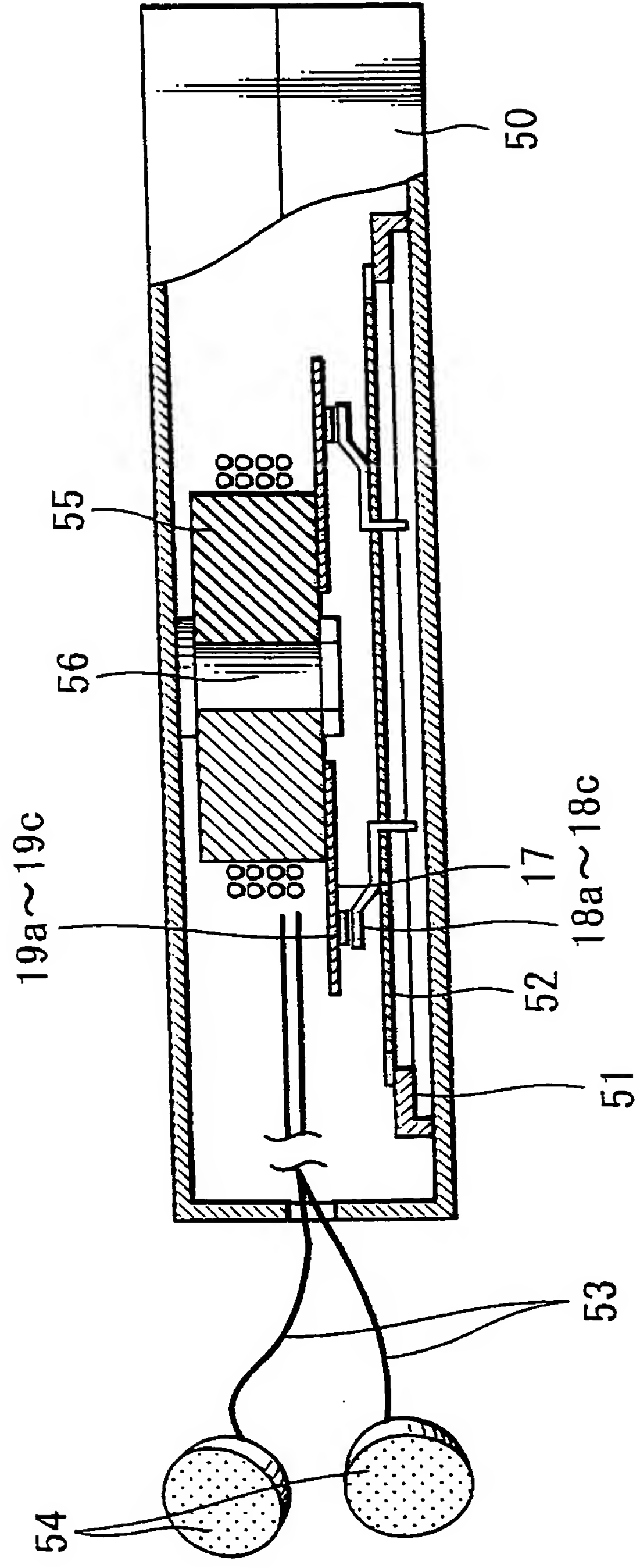


FIG. 7B

FIG. 8

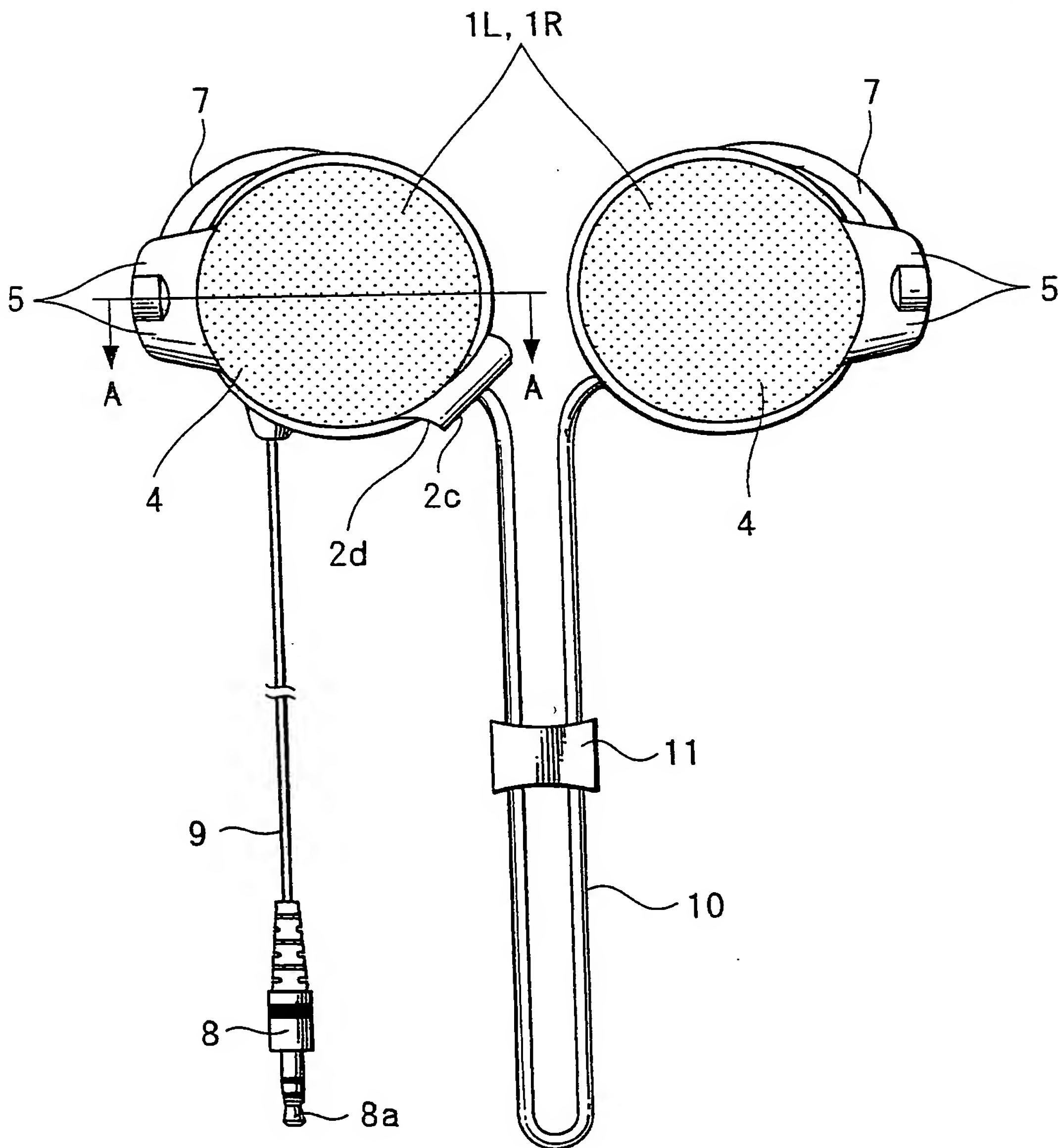


FIG. 9

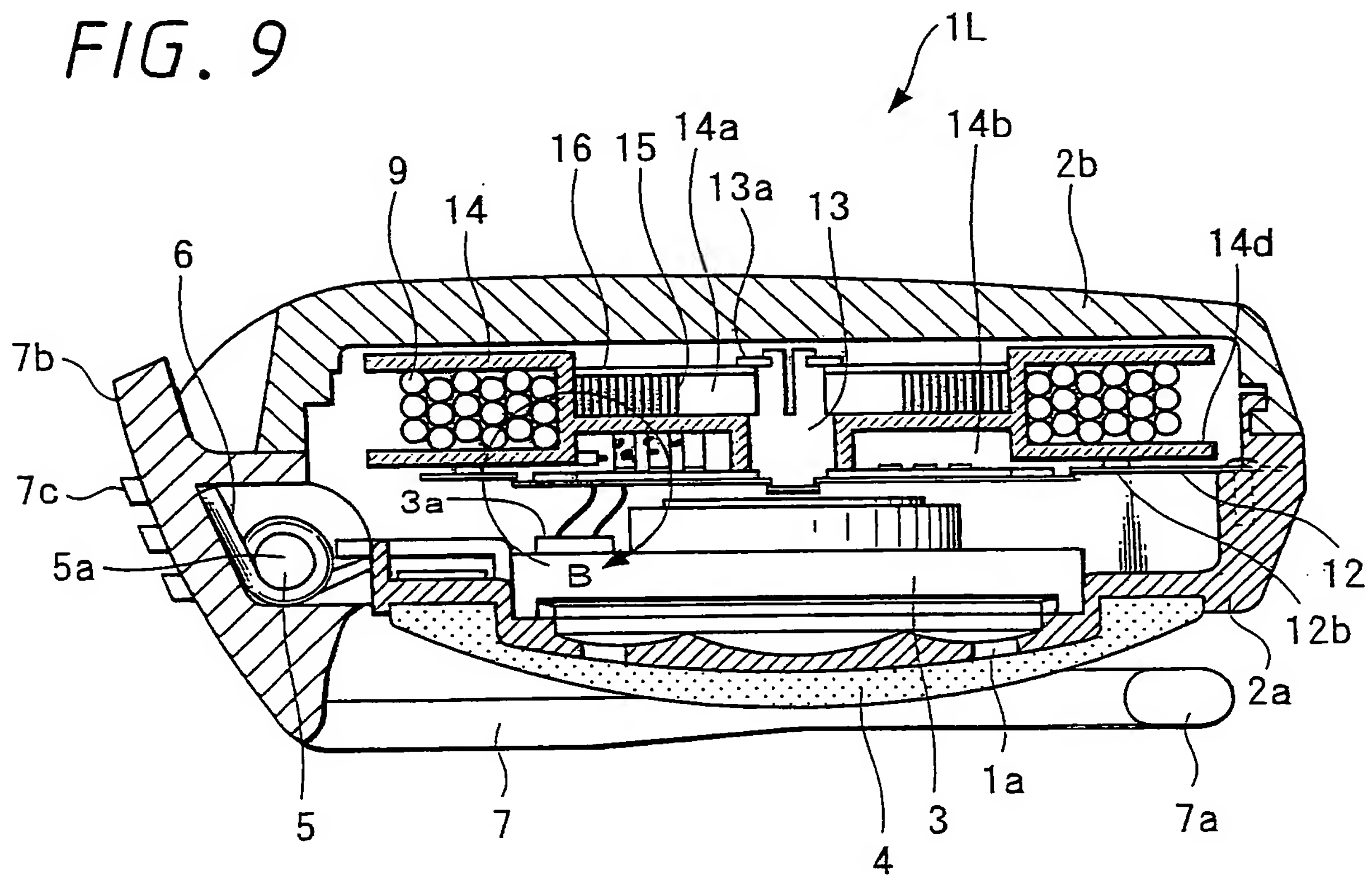


FIG. 10

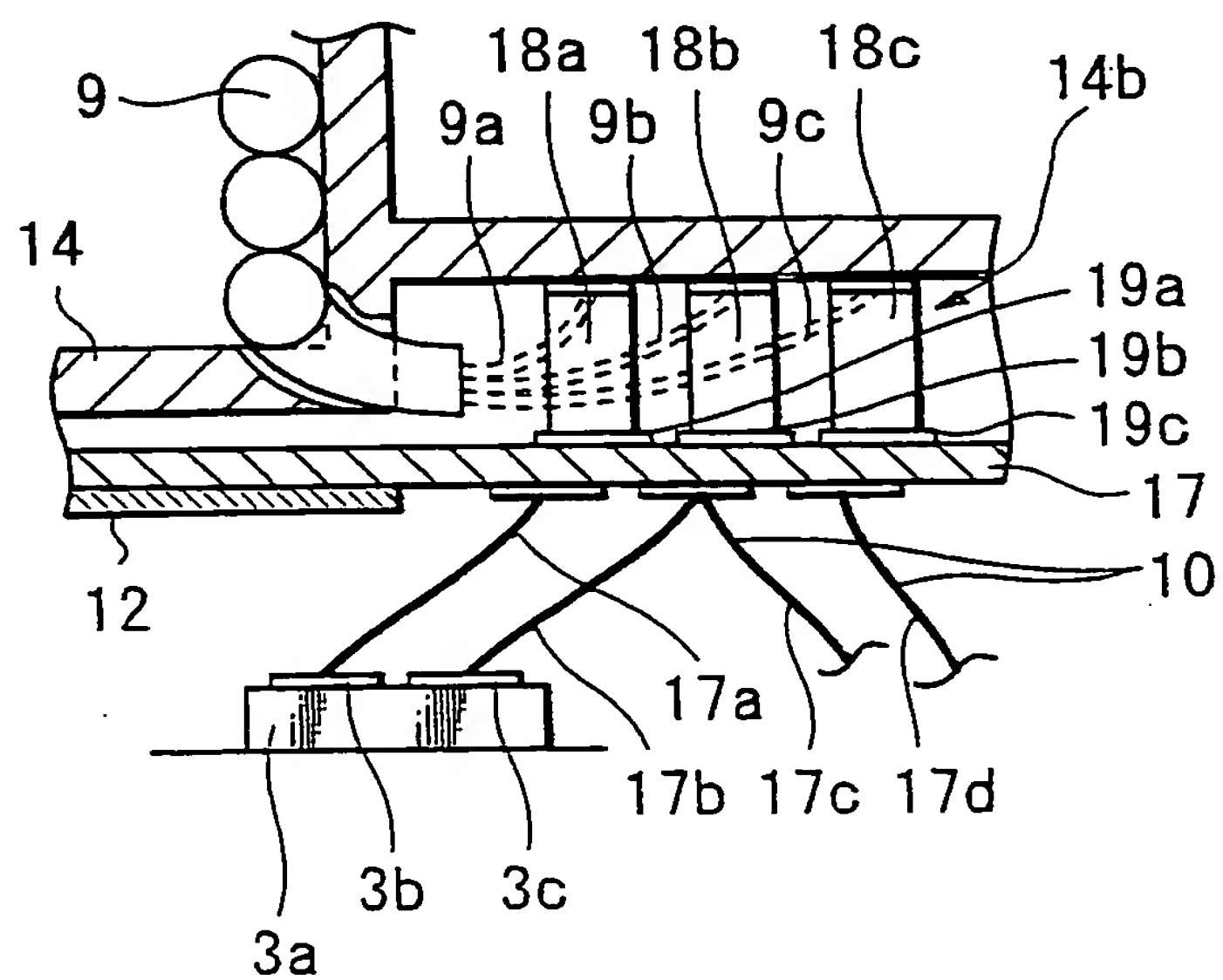


FIG. 12A

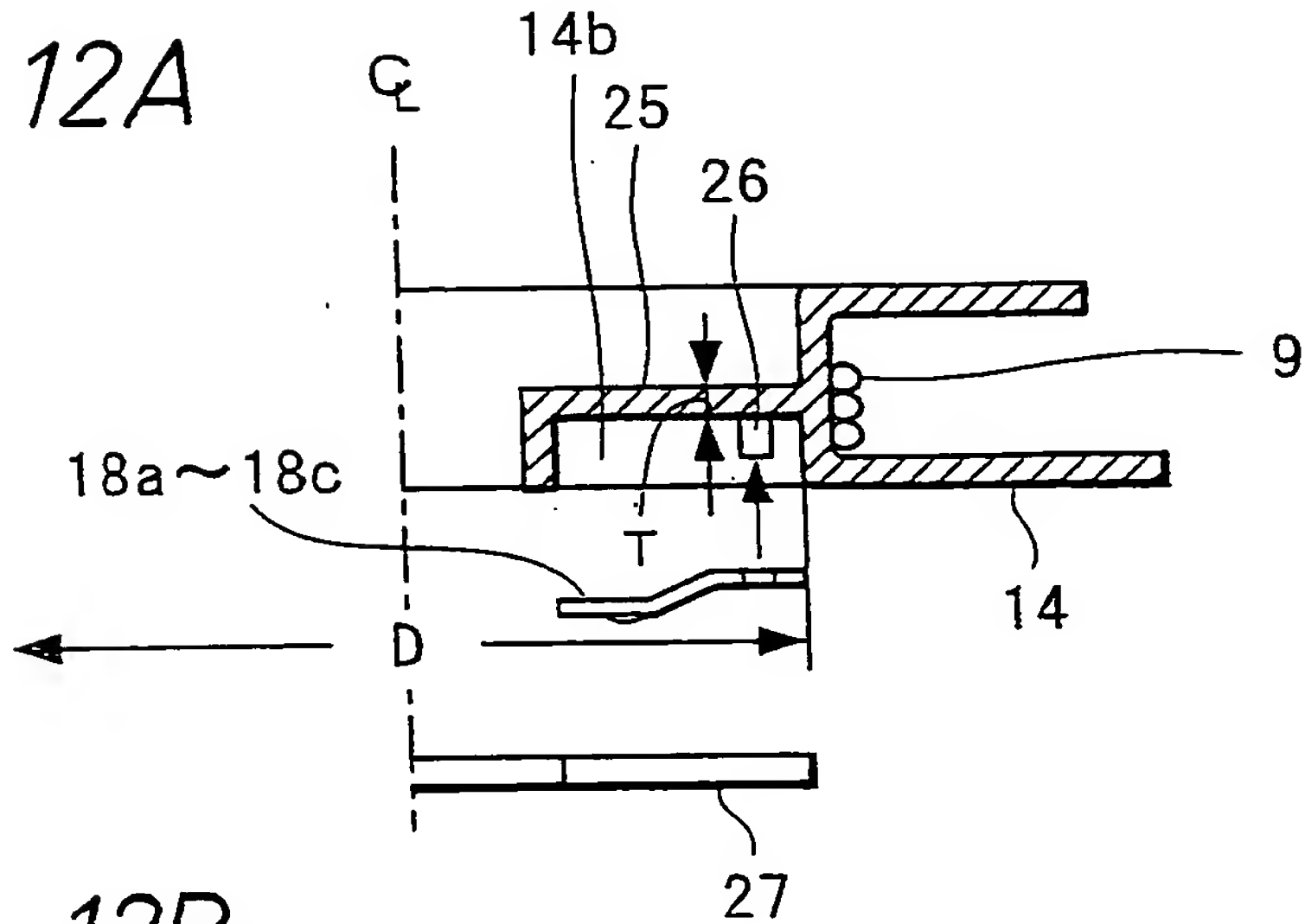


FIG. 12B

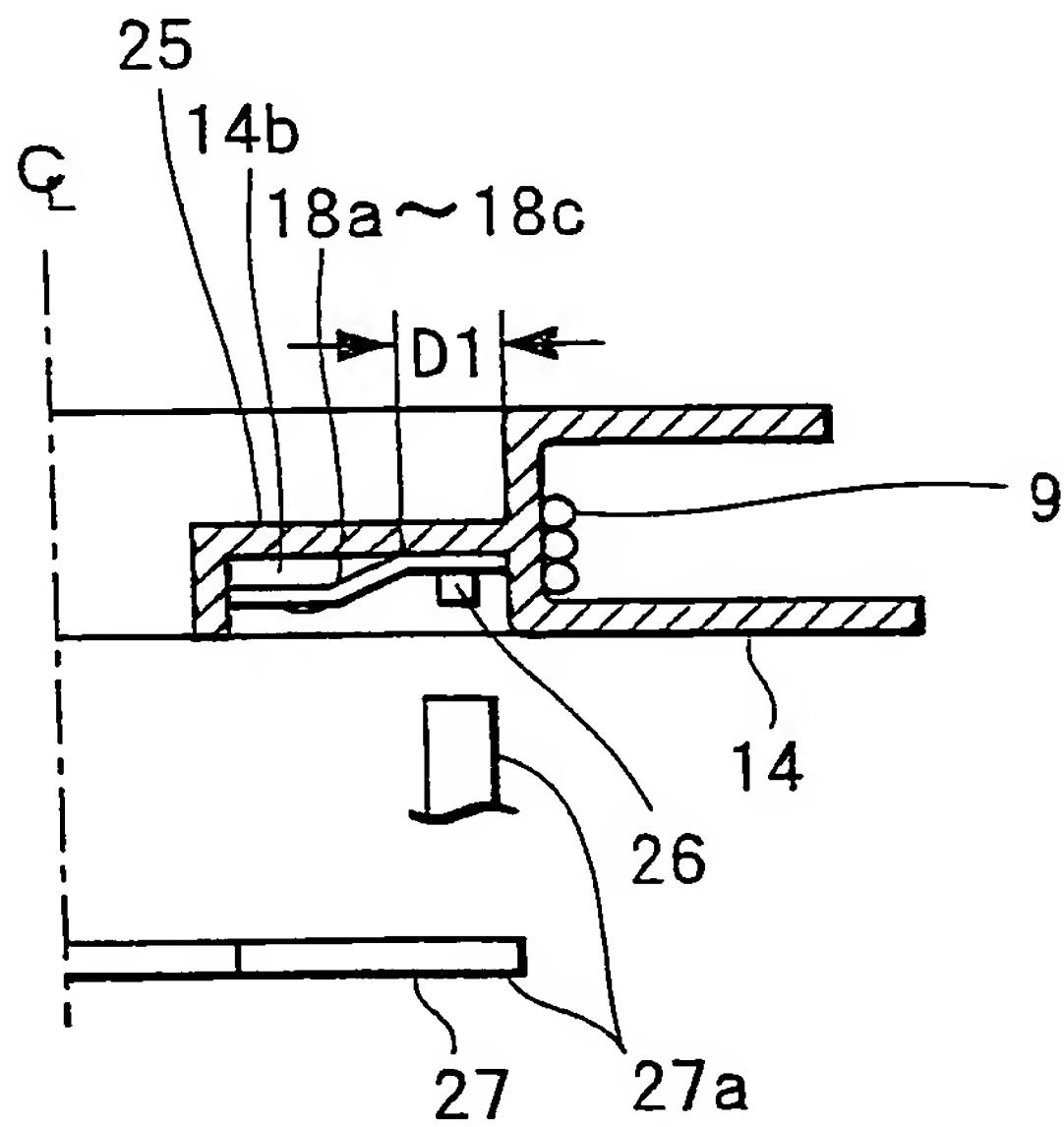
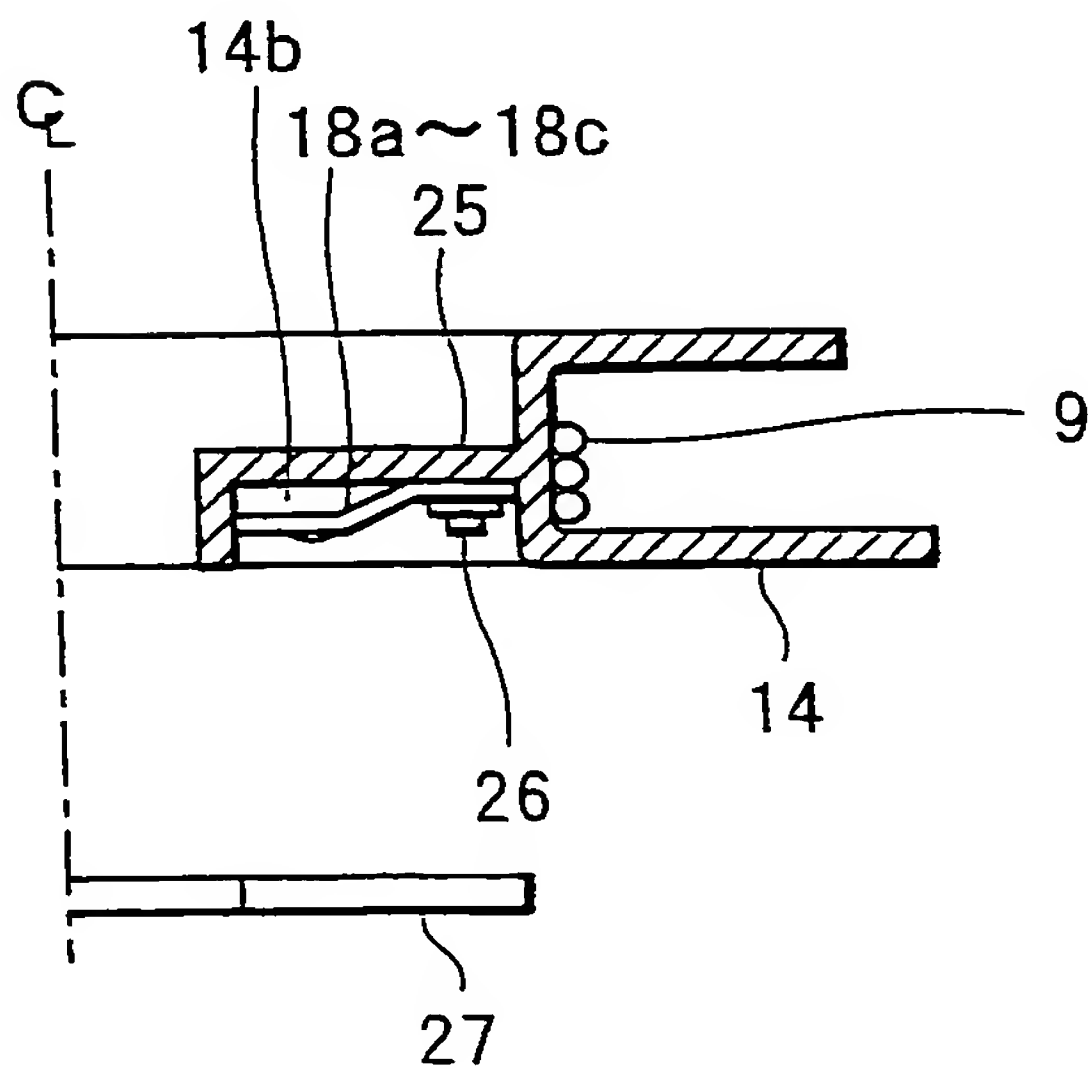


FIG. 12C



DESCRIPTION OF REFERENCE NUMERALS

1L, 1R ... LEFT/RIGHT HEADPHONE HOUSING

2 ... HOUSING

2a ... FRONT HOUSING

2b ... REAR HOUSING

2d ... INSERTION OPENING

3 ... D/U (LOUDSPEAKER)

4 ... EAR PAD

5 ... SPINDLE PORTION

5a ... SPINDLE

6 ... COILED SPRING

7 ... EAR HOOK

8 ... INPUT PLUG

8a ... CONNECTION TERMINAL

9 ... INPUT CORD

10 ... PASSAGE CORD

12 ... BOARD

13 ... ROTATING SHAFT

14 ... REEL

14d, 14e ... UPPER/LOWER FLANGE

15 ... SPRING

17 ... TERMINAL BOARD

18a, 18b, 18c ... CONTACT POINT (BRUSH)

19a, 19b, 19c ... METAL SLIP RING

21 ... LOCKING PIECE

21a ... OPERATIONAL PORTION

21b ... LOCKING PORTION